

AMENDMENTS TO THE CLAIMS:

Kindly replace the previous claim set with the claim set that appears below, in which Claims 1, 7 and 25 have been amended to read as follows:

1. (Currently Amended) A photocurable encapsulant composition comprising:

- (i) a uv curable component;
- (ii) a component for initiating cure of the uv curable component;
- (iii) an opacifying component which has a first colour which is sufficiently transparent to uv light so as to substantially unaffected cure of the uv curable component and which is activatable to change colour to a second colour which is sufficiently opaque to render the cured product of the composition substantially opaque to visible light; and

(iv) an adhesion-promoting component,
wherein the composition, when applied on a part as an encapsulant composition, achieves sufficient cure through volume after exposure to uv light to allow a sufficient thickness of the encapsulant composition to cure on the part so that the encapsulant composition is opaque and the part is not visible through the encapsulant composition.

2. (Original) A composition according to Claim 1, wherein the composition is capable of curing through a volume of at least about 1 mm.

3. (Previously Presented) A composition according to Claim 1, wherein the composition is capable of curing radiation at a wavelength of at least 290 nm.

4. (Previously Presented) A composition according to Claim 1 further comprising an inorganic filler component.

5. (Previously Presented) A composition according to Claim 1, wherein the composition is capable of curing in a time of less than about 15 seconds.

6. (Previously Presented) A composition according to Claim 1 wherein the uv curable component comprises an epoxy resin material.

7. (Currently Amended) A composition according to Claim 6, wherein the epoxy resin component is a member selected from the group consisting of cycloaliphatic epoxy resins; ~~C₄-C₂₈~~ alkyl glycidyl ethers; ~~C₂-C₂₈~~ alkyl and alkenyl glycidyl

~~esters; C₁-C₂₈ alkyl, mono~~ and poly-phenol glycidyl ethers;
polyglycidyl ethers of pyrocatechol, resorcinol, hydroquinone,
4,4'-dihydroxydiphenyl methane, 4,4'-dihydroxy-3,3'-
dimethyldiphenyl methane, 4,4'-dihydroxydiphenyl dimethyl
methane, 4,4'-dihydroxydiphenyl methyl methane, 4,4'-
dihydroxydiphenyl cyclohexane, 4,4'-dihydroxy-3,3'-
dimethyldiphenyl propane, 4,4'-dihydroxydiphenyl sulfone, and
tris(4-hydroxyphenyl)methane; polyglycidyl ethers of the
chlorination and bromination products of the above-mentioned
diphenols; polyglycidyl ethers of novolacs; polyglycidyl ethers
of diphenols obtained by esterifying ethers of diphenols
obtained by esterifying salts of an aromatic hydrocarboxylic
acid with a dihaloalkane or dihalogen dialkyl ether;
polyglycidyl ethers of polyphenols obtained by condensing
phenols and long-chain halogen paraffins containing at least two
halogen atoms; phenol novolac epoxy resins; cresol novolac epoxy
resins; and combinations thereof.

8. (Previously Presented) A composition according to
Claim 6 wherein the epoxy resin component is a cycloaliphatic
epoxy resin, bisphenol A epoxy resin, bisphenol F epoxy resin
and combinations thereof.

9. (Previously Presented) A composition according to any one of Claim 6, wherein the epoxy resin component is used in an amount of up to about 98 percent by weight of the total composition.

10. (Previously Presented) A composition according to Claim 1 wherein the opacifying component comprises a lactone in which an aromatic ring is fused to the lactone ring.

11. (Previously Presented) A composition according to Claim 1 wherein the component for initiating cure of the curable component also participates in the colour change of the opacifying component.

12. (Previously Presented) A composition according to Claim 1 wherein the component for initiating cure of the curable component is an onium salt.

13. (Previously Presented) A composition according to Claim 1 wherein the adhesion promoting component comprises silane.

14. (Original) A composition according to Claim 13 wherein the silane is selected from the group consisting of: cycloaliphatic silanes, epoxy silanes, and amino silanes and combinations thereof.

15. (Previously Presented) A composition according to Claim 1 wherein the composition further comprises a photosensitiser component.

16. (Original) A composition according to Claim 15, wherein the photosensitiser component is selected from the group consisting of thioxanthenes, anthracene, perylene, phenothazine, 1,2 benzathracene, coronene, pyrene, tetracene and combinations thereof.

17. (Previously Presented) A composition according to Claim 15, wherein the photosensitiser is a thioxanthone.

18. (Previously Presented) A composition according to Claim 15, wherein the photosensitiser is used in an amount within the range of about 0.01 to 1 percent by weight of the total composition.

19. (Previously Presented) A composition according to Claim 1, wherein component for initiating cure of the uv curable component is present in an amount within the range of about 0.1 to about 2 percent by weight of the total composition.

20. (Previously Presented) A composition according to Claim 1, further comprising a dye or pigment.

21. (Withdrawn) A smart card module assembly,
comprising:

a carrier substrate dimensioned to receive a die;
a die having two surfaces, a first of which
having bond pads disposed thereon and a second of which
dimensioned for placement on the carrier substrate, wherein the
second surface of the die is disposed on the carrier substrate
so that the bond pads on the first surface of the die are in a
position relative to the bond pads on the carrier substrate to
make electrical connection therewith by way of the wire
connectors;

a plurality of bond pads, some of which being
positioned on one surface of the die and others of which being
positioned on the carrier substrate;

a plurality of wire connectors; and

a composition according to any preceding claim, wherein the second surface of the die is disposed on the carrier substrate so that the bond pads on the first surface of the die are in a position relative to the bond pads on the carrier substrate to make electrical connection therewith by way of the wire connectors, and wherein the composition is disposed over at least a portion of the smart card module assembly so as to cover the wire bond connections established.

22. (Withdrawn) A smart card comprising:

a plastic card; and

a smart card module assembly of Claim 21 having been exposed to radiation in the electromagnetic radiation at a wavelength of at least 290 nm, encased in the plastic card.

23. (Withdrawn) A method for the attachment of an integrated circuit to a carrier substrate, the steps of which include

applying a composition according to Claim 1 to the carrier substrate;

activating the composition prior to or after application thereof through exposure to radiation in the electromagnetic spectrum; and

positioning the integrated circuit onto the circuit board and establishing electrical interconnection therebetween; and

optionally, curing the composition at a temperature between 60 and 140°C.

24. (Cancelled).

25. (Currently Amended) [Use] A method of applying a composition according to Claim 1 as an encapsulant for encapsulating electronic components comprising the steps of:

(i) applying the composition onto a part as an encapsulant;
and

(ii) exposing the composition to uv light so as to achieve sufficient cure through volume on exposure to the uv light to allow a sufficient thickness of the encapsulant composition to cure on the part so that the encapsulant composition is opaque and the part is not visible through the encapsulant composition.